FAIRCHILD SEMICONDUCTOR®

January 2008

# 74LVT573, 74LVTH573
# Low Voltage Octal Transparent Latch with 3-STATE Outputs

## Features

- Input and output interface capability to systems at 5V $V_{CC}$
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH573), also available without bushold feature (74LVT573)
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink –32mA/+64mA
- Functionally compatible with the 74 series 573
- Latch-up performance exceeds 500mA
- ESD performance:
  - Human-body model > 2000V
  - Machine model > 200V
  - Charged-device model > 1000V

## General Description

The LVT573 and LVTH573 consist of eight latches with 3-STATE outputs for bus organized system applications. The latches appear transparent to the data when Latch Enable (LE) is HIGH. When LE is low, the data satisfying the input timing requirements is latched. Data appears on the bus when the Output Enable ($\overline{OE}$) is LOW. When $\overline{OE}$ is HIGH, the bus output is in the high impedance state.

The LVTH573 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs.

These octal latches are designed for low-voltage (3.3V) $V_{CC}$ applications, but with the capability to provide a TTL interface to a 5V environment. The LVT573 and LVTH573 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining a low power dissipation.

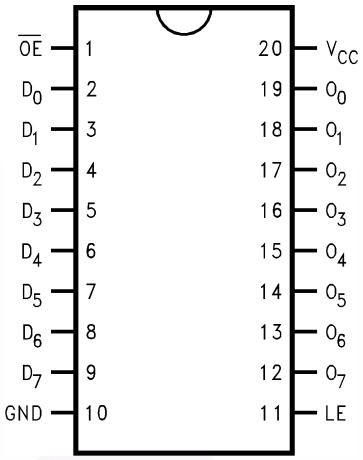
## Ordering Information

| Order Number | Package Number | Package Description |
|---|---|---|
| 74LVT573WM | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 74LVT573SJ | M20D | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LVT573MSA | MSA20 | 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide |
| 74LVT573MTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |
| 74LVTH573WM | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 74LVTH573SJ | M20D | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LVTH573MSA | MSA20 | 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide |
| 74LVTH573MTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

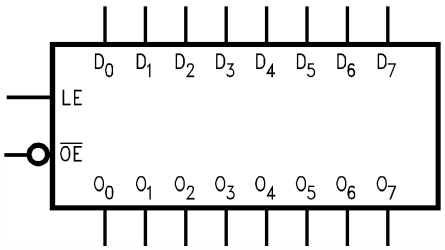
Device also available in Tape and Reel. Specify by appending suffix letter “X” to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

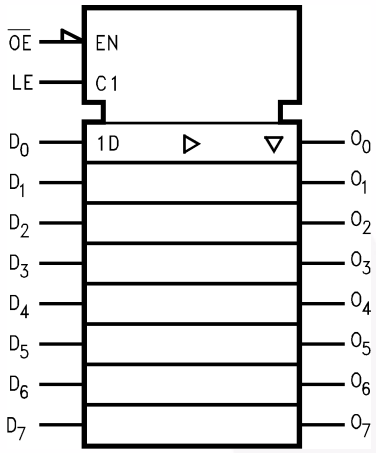
## Connection Diagram




## Logic Symbols




IEEE/IEC




## Pin Description

| Pin Names | Description |
|---|---|
| $D_0$–$D_7$ | Data Inputs |
| LE | Latch Enable Input |
| $\overline{OE}$ | Output Enable Input |
| $O_0$–$O_7$ | 3-STATE Latch Outputs |

## Functional Description

The LVT573 and LVTH573 contain eight D-type latches with 3-STATE standard outputs. When the Latch Enable (LE) input is HIGH, data on the $D_n$ inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D-type input changes. When LE is LOW, the latches store the information that was present on the D-type inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-STATE standard outputs are controlled by the Output Enable ($\overline{OE}$) input. When $\overline{OE}$ is LOW, the standard outputs are in the 2-state mode. When $\overline{OE}$ is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the latches.

## Truth Table

| Inputs | | | Outputs |
|---|---|---|---|
| **LE** | **$\overline{OE}$** | **$D_n$** | **$O_n$** |
| X | H | X | Z |
| H | L | L | L |
| H | L | H | H |
| L | L | X | $O_0$ |

H = HIGH Voltage Level

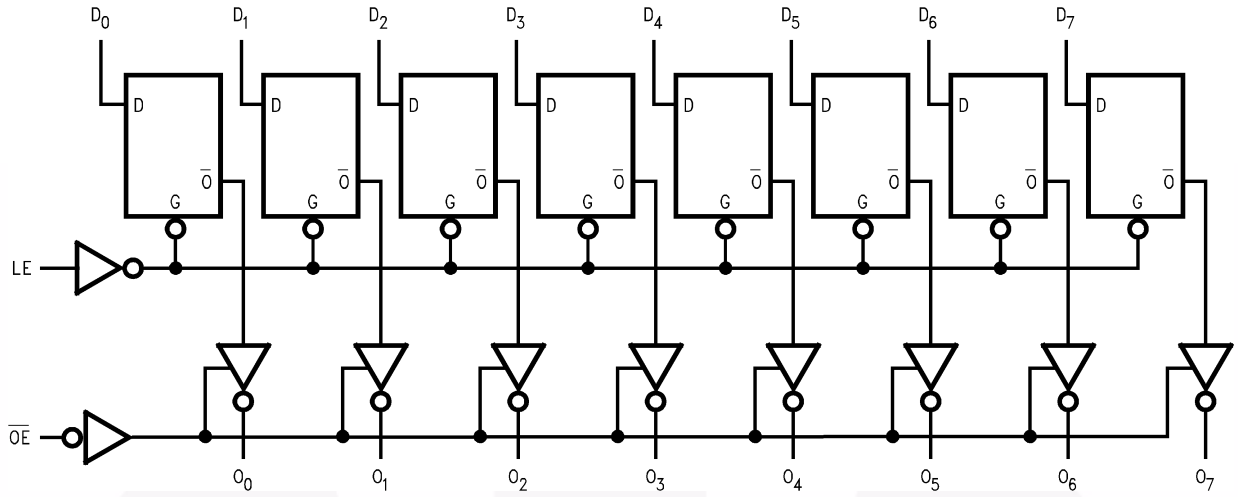
L = LOW Voltage Level

Z = High Impedance

X = Immaterial

$O_0$ = Previous $O_0$ before HIGH to LOW transition of Latch Enable

## Logic Diagram




Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating |
|---|---|---|
| $V_{CC}$ | Supply Voltage | –0.5V to +4.6V |
| $V_I$ | DC Input Voltage | –0.5V to +7.0V |
| $V_O$ | DC Output Voltage | |
| | Output in 3-STATE | –0.5V to +7.0V |
| | Output in HIGH or LOW State(1) | –0.5V to +7.0V |
| $I_{IK}$ | DC Input Diode Current, $V_I$ < GND | –50mA |
| $I_{OK}$ | DC Output Diode Current, $V_O$ < GND | –50mA |
| $I_O$ | DC Output Current, $V_O > V_{CC}$ | |
| | Output at HIGH State | 64mA |
| | Output at LOW State | 128mA |
| $I_{CC}$ | DC Supply Current per Supply Pin | ±64mA |
| $I_{GND}$ | DC Ground Current per Ground Pin | ±128mA |
| $T_{STG}$ | Storage Temperature | –65°C to +150°C |

**Note:**

1. $I_O$ Absolute Maximum Rating must be observed.

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol | Parameter | Min | Max | Units |
|---|---|---|---|---|
| $V_{CC}$ | Supply Voltage | 2.7 | 3.6 | V |
| $V_I$ | Input Voltage | 0 | 5.5 | V |
| $I_{OH}$ | HIGH-Level Output Current | | –32 | mA |
| $I_{OL}$ | LOW-Level Output Current | | 64 | mA |
| $T_A$ | Free-Air Operating Temperature | –40 | 85 | °C |
| $\Delta t / \Delta V$ | Input Edge Rate, $V_{IN}$ = 0.8V–2.0V, $V_{CC}$ = 3.0V | 0 | 10 | ns/V |

## DC Electrical Characteristics

| Symbol | Parameter | $V_{CC}$ (V) | Conditions | $T_A = -40°C$ to $+85°C$ | | | Units |
|---|---|---|---|---|---|---|---|
| | | | | Min. | Typ.(2) | Max. | |
| $V_{IK}$ | Input Clamp Diode Voltage | 2.7 | $I_I = -18mA$ | | | –1.2 | V |
| $V_{IH}$ | Input HIGH Voltage | 2.7–3.6 | $V_O \le 0.1V$ or $V_O \ge V_{CC} - 0.1V$ | 2.0 | | | V |
| $V_{IL}$ | Input LOW Voltage | 2.7–3.6 | | | | 0.8 | V |
| $V_{OH}$ | Output HIGH Voltage | 2.7–3.6 | $I_{OH} = -100\mu A$ | $V_{CC} - 0.2$ | | | V |
| | | 2.7 | $I_{OH} = -8mA$ | 2.4 | | | |
| | | 3.0 | $I_{OH} = -32mA$ | 2.0 | | | |
| $V_{OL}$ | Output LOW Voltage | 2.7 | $I_{OL} = 100\mu A$ | | | 0.2 | V |
| | | | $I_{OL} = 24mA$ | | | 0.5 | |
| | | 3.0 | $I_{OL} = 16mA$ | | | 0.4 | |
| | | | $I_{OL} = 32mA$ | | | 0.5 | |
| | | | $I_{OL} = 64mA$ | | | 0.55 | |
| $I_{I(HOLD)}$(3) | Bushold Input Minimum Drive | 3.0 | $V_I = 0.8V$ | 75 | | | μA |
| | | | $V_I = 2.0V$ | –75 | | | |
| $I_{I(OD)}$(3) | Bushold Input Over-Drive Current to Change State | 3.0 | (4) | 500 | | | μA |
| | | | (5) | –500 | | | |
| $I_I$ | Input Current | 3.6 | $V_I = 5.5V$ | | | 10 | μA |
| | Control Pins | 3.6 | $V_I = 0V$ or $V_{CC}$ | | | ±1 | |
| | Data Pins | 3.6 | $V_I = 0V$ | | | –5 | |
| | | | $V_I = V_{CC}$ | | | 1 | |
| $I_{OFF}$ | Power Off Leakage Current | 0 | $0V \le V_I$ or $V_O \le 5.5V$ | | | ±100 | μA |
| $I_{PU/PD}$ | Power up/down 3-STATE Output Current | 0–1.5 | $V_O = 0.5V$ to $3.0V$, $V_I$ = GND or $V_{CC}$ | | | ±100 | μA |
| $I_{OZL}$ | 3-STATE Output Leakage Current | 3.6 | $V_O = 0.5V$ | | | –5 | μA |
| $I_{OZH}$ | 3-STATE Output Leakage Current | 3.6 | $V_O = 3.0V$ | | | 5 | μA |
| $I_{OZH}+$ | 3-STATE Output Leakage Current | 3.6 | $V_{CC} < V_O \le 5.5V$ | | | 10 | μA |
| $I_{CCH}$ | Power Supply Current | 3.6 | Outputs HIGH | | | 0.19 | mA |
| $I_{CCL}$ | Power Supply Current | 3.6 | Outputs LOW | | | 5 | mA |
| $I_{CCZ}$ | Power Supply Current | 3.6 | Outputs Disabled | | | 0.19 | mA |
| $I_{CCZ}+$ | Power Supply Current | 3.6 | $V_{CC} \le V_O \le 5.5V$, Outputs Disabled | | | 0.19 | mA |
| $\Delta I_{CC}$ | Increase in Power Supply Current(6) | 3.6 | One Input at $V_{CC} - 0.6V$, Other Inputs at $V_{CC}$ or GND | | | 0.2 | mA |

**Notes:**

2. All typical values are at $V_{CC} = 3.3V$, $T_A = 25°C$.
3. Applies to bushold versions only (74LVTH573).
4. An external driver must source at least the specified current to switch from LOW-to-HIGH.
5. An external driver must sink at least the specified current to switch from HIGH-to-LOW.
6. This is the increase in supply current for each input that is at the specified voltage level rather than $V_{CC}$ or GND.

## Dynamic Switching Characteristics[7]

| Symbol | Parameter | $V_{CC}$ (V) | Conditions | $T_A$ = 25°C | | | Units |
|---|---|---|---|---|---|---|---|
| | | | $C_L$ = 50pF, $R_L$ = 500Ω | Min. | Typ. | Max. | |
| $V_{OLP}$ | Quiet Output Maximum Dynamic $V_{OL}$ | 3.3 | [8] | | 0.8 | | V |
| $V_{OLV}$ | Quiet Output Minimum Dynamic $V_{OL}$ | 3.3 | [8] | | –0.8 | | V |

**Notes:**

7. Characterized in SOIC package. Guaranteed parameter, but not tested.
8. Max number of outputs defined as (n). n–1 data inputs are driven 0V to 3V. Output under test held LOW.

## AC Electrical Characteristics

| Symbol | Parameter | $T_A$ = –40°C to +85°C, $C_L$ = 50pF, $R_L$ = 500Ω | | | | | Units |
|---|---|---|---|---|---|---|---|
| | | $V_{CC}$ = 3.3V ± 0.3V | | | $V_{CC}$ = 2.7V | | |
| | | Min. | Typ.[9] | Max. | Min. | Max. | |
| $t_{PHL}$ | Propagation Delay, $D_n$ to $O_n$ | 1.5 | | 4.4 | 1.5 | 4.9 | ns |
| $t_{PLH}$ | | 1.5 | | 4.1 | 1.5 | 4.7 | |
| $t_{PHL}$ | Propagation Delay, LE to $O_n$ | 1.9 | | 4.4 | 1.9 | 4.9 | ns |
| $t_{PLH}$ | | 1.9 | | 4.4 | 1.9 | 5.0 | |
| $t_{PZL}$ | Output Enable Time | 1.5 | | 5.1 | 1.5 | 6.6 | ns |
| $t_{PZH}$ | | 1.5 | | 5.1 | 1.5 | 5.9 | |
| $t_{PLZ}$ | Output Disable Time | 2.0 | | 4.6 | 2.0 | 4.9 | ns |
| $t_{PHZ}$ | | 2.0 | | 4.9 | 2.0 | 5.5 | |
| $t_S$ | Setup Time, $D_n$ to LE | 0.7 | | | 0.6 | | ns |
| $t_H$ | Hold Time, $D_n$ to LE | 1.5 | | | 1.7 | | ns |
| $t_W$ | LE Pulse Width | 3.0 | | | 3.0 | | ns |
| $t_{OSHL}$, $t_{OSLH}$ | Output to Output Skew[10] | | | 1.0 | | 1.0 | ns |

**Notes:**

9. All typical values are at $V_{CC}$ = 3.3V, $T_A$ = 25°C.
10. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW ($t_{OSHL}$) or LOW-to-HIGH ($t_{OSLH}$).

## Capacitance[11]

| Symbol | Parameter | Conditions | Typical | Units |
|---|---|---|---|---|
| $C_{IN}$ | Input Capacitance | $V_{CC}$ = Open, $V_I$ = 0V or $V_{CC}$ | 4 | pF |
| $C_{OUT}$ | Output Capacitance | $V_{CC}$ = 3.0V, $V_O$ = 0V or $V_{CC}$ | 6 | pF |

**Note:**

11. Capacitance is measured at frequency f = 1MHz, per MIL-STD-883, Method 3012.

## Physical Dimensions

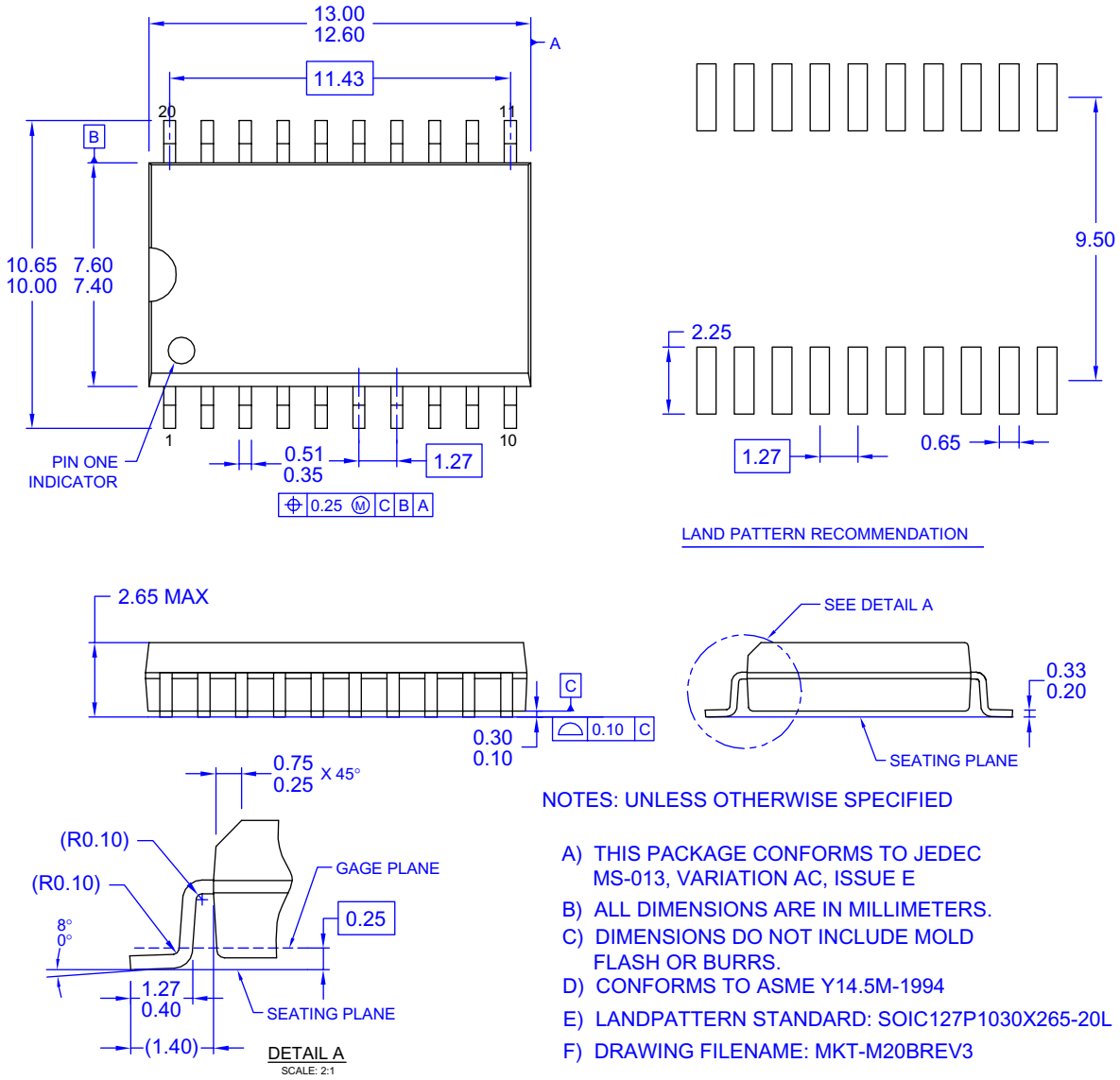



**Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide**

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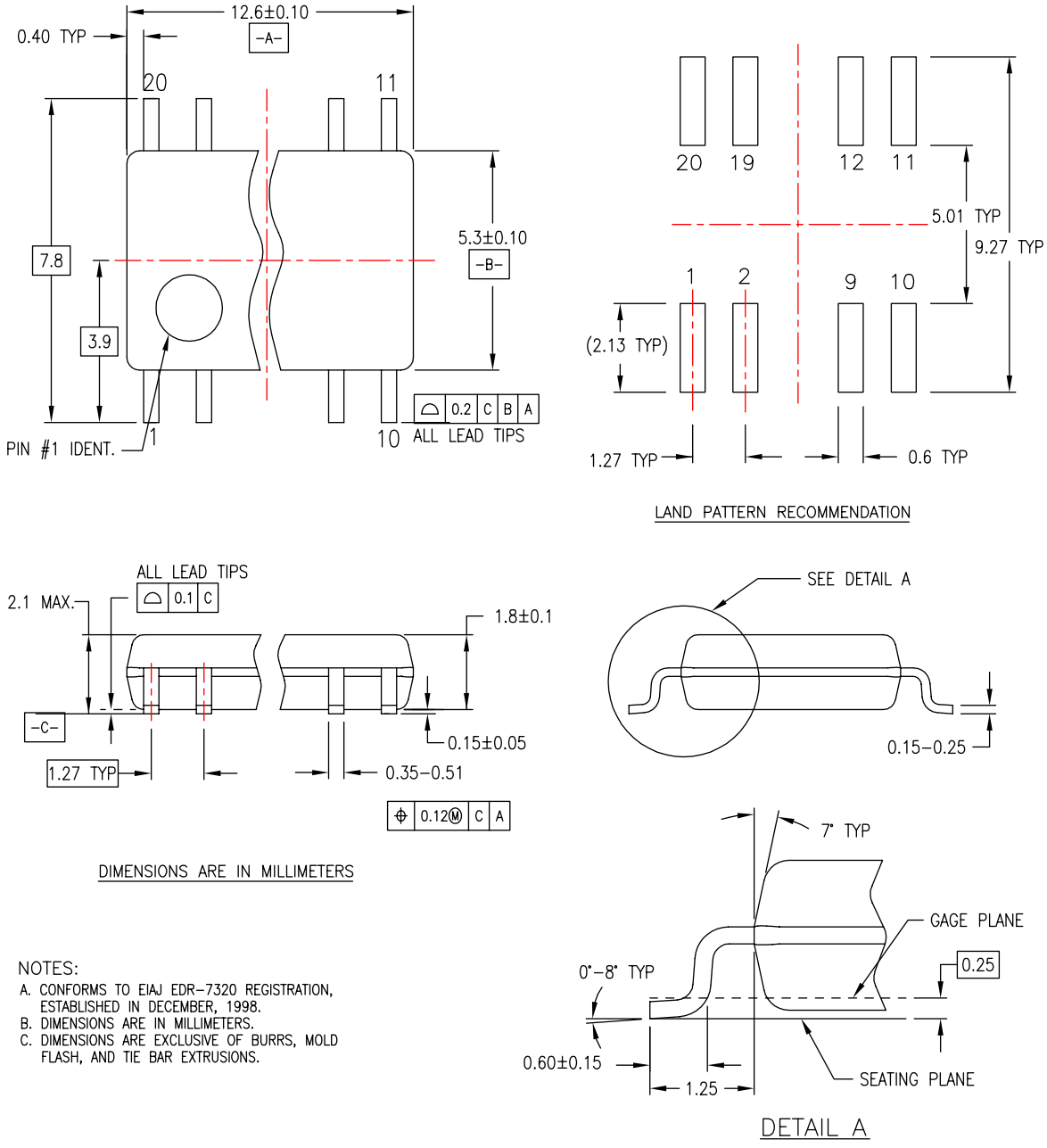
## Physical Dimensions (Continued)




NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DREVC

**Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide**

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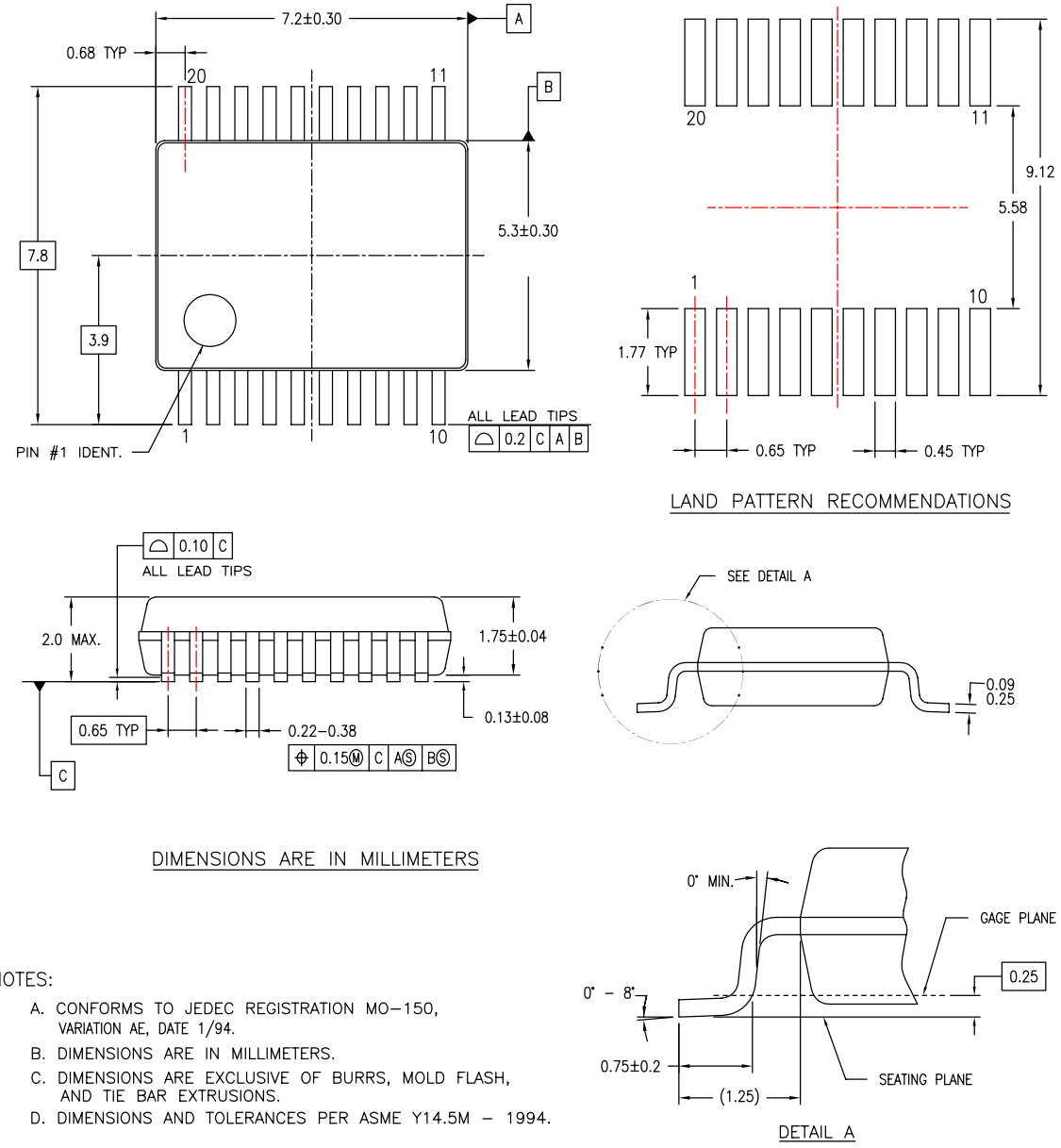
## Physical Dimensions (Continued)




NOTES:

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D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M – 1994.

MSA20REVB

**Figure 3. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide**

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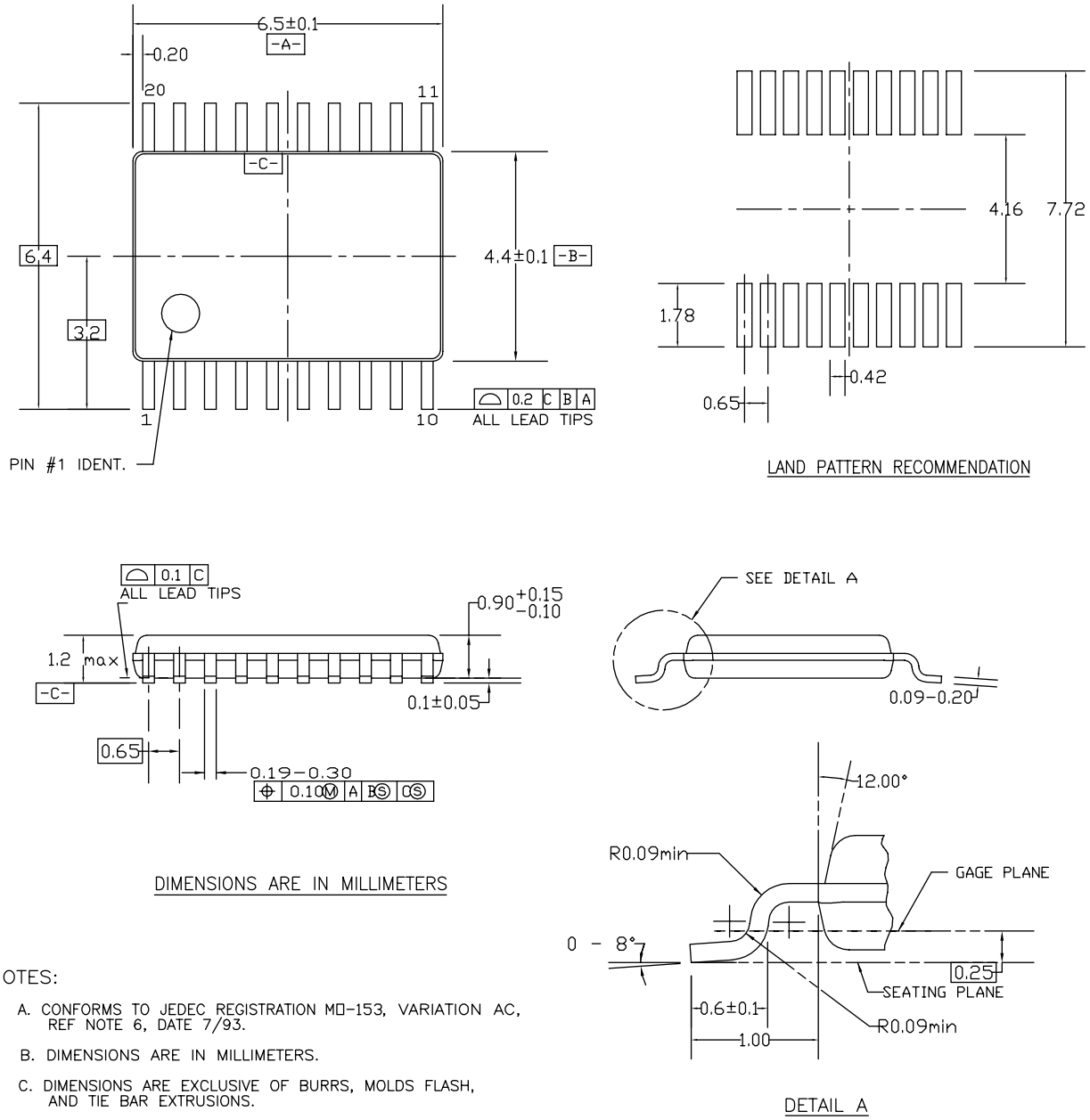
## Physical Dimensions (Continued)




DIMENSIONS ARE IN MILLIMETERS

NOTES:

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D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

**Figure 4. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide**

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Rev. I33

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